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Part Number: [0783150011](#)
Status: **Active**
Description: 1.00mm (.039") Pitch DDR3 DIMM Socket, Very Low Profile, Vertical, Press-Fit, with Pegs, Black Housing and Latches, 0.76µm (30µ") Gold (Au)Plating, 2.85mm (.112") Compliant Pin Length, 2.60mm (.102") PCB Thickness, 240 Circuits, Lead free

Documents:

[Drawing \(PDF\)](#) [RoHS Certificate of Compliance \(PDF\)](#)
[Product Specification PS-78315-001 \(PDF\)](#)

General

Product Family	Memory Module Sockets
Series	78315
Component Type	Socket
JEDEC Outline	MO-269
Product Name	DDR3 DIMM

Physical

Circuits (Loaded)	240
Circuits (maximum)	240
Color - Resin	Black
Durability (mating cycles max)	25
Entry Angle	Vertical
Function Key	None
Keying to Mating Part	Yes
Material - Metal	Copper Alloy
Material - Plating Mating	Gold
Material - Plating Termination	Tin
Material - Resin	Nylon
PC Tail Length (in)	0.112 In
PC Tail Length (mm)	2.85 mm
PCB Locator	Yes
PCB Retention	Yes
PCB Thickness Recommended (in)	0.102 In
PCB Thickness Recommended (mm)	2.60 mm
Packaging Type	Tray
Pitch - Mating Interface (in)	0.039 In
Pitch - Mating Interface (mm)	1.00 mm
Pitch - Term. Interface (in)	0.039 In
Pitch - Term. Interface (mm)	1.00 mm
Plating min: Mating (µin)	30
Plating min: Mating (µm)	0.76
Plating min: Termination (µin)	15
Plating min: Termination (µm)	0.38
Temperature Range - Operating	-55°C to +85°C
Termination Interface: Style	Through Hole - Compliant Pin

Electrical

Current - Maximum per Contact	1A
Voltage - Maximum	30V AC (RMS)/DC
Voltage Key	Center

Material Info

Reference - Drawing Numbers

Application Specification	AS-78315-001
Product Specification	PS-78315-001, RPS-78315-001

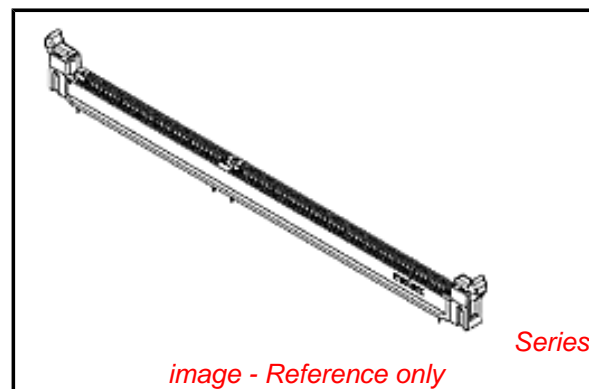


image - Reference only

EU RoHS

**ELV and RoHS
Compliant**
**REACH SVHC
Contains SVHC: No**
Halogen-Free
**Status
Not Reviewed**

China RoHS



**Need more information on product
environmental compliance?**

Email productcompliance@molex.com
 For a multiple part number RoHS Certificate of Compliance, [click here](#)

Please visit the [Contact Us](#) section for any non-product compliance questions.

Search Parts in this Series

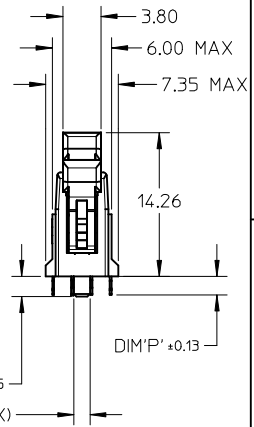
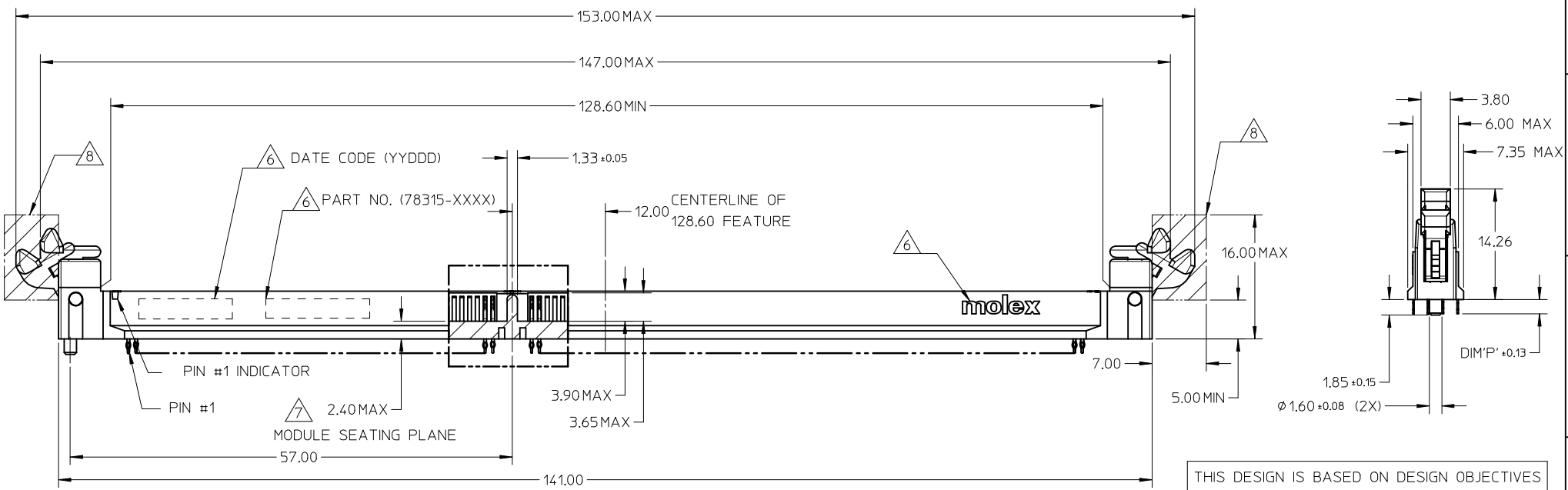
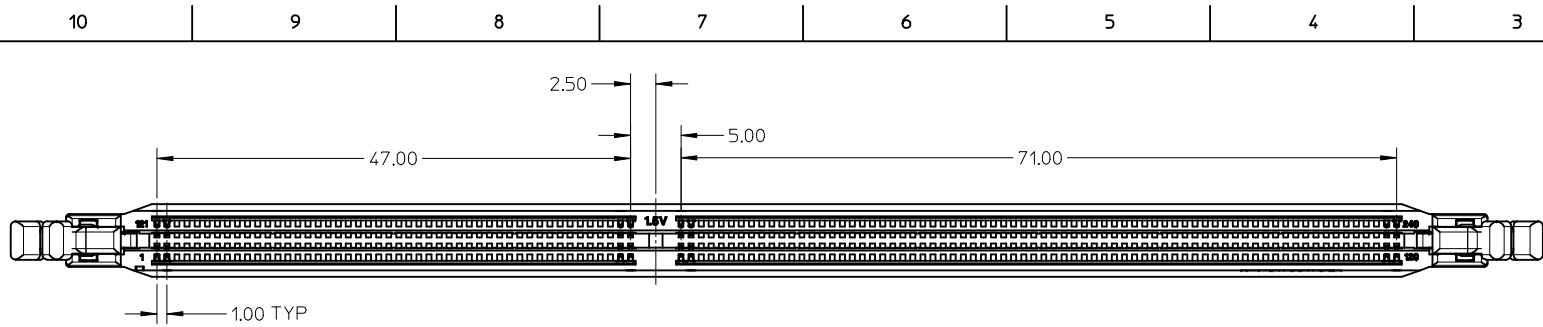
[78315Series](#)

Mates With

JEDEC standard 1.27mm modules

This document was generated on 05/17/2010

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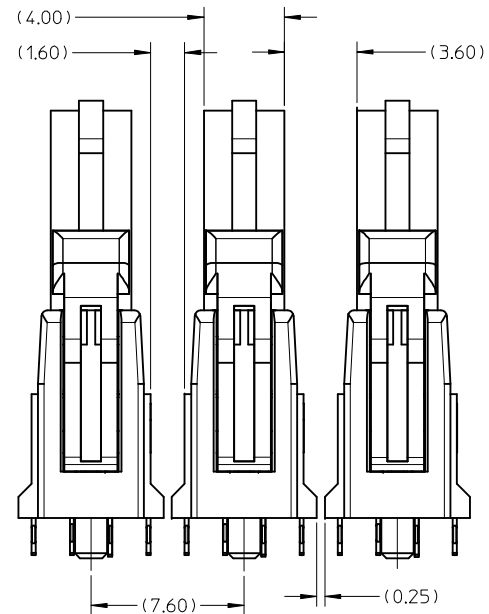
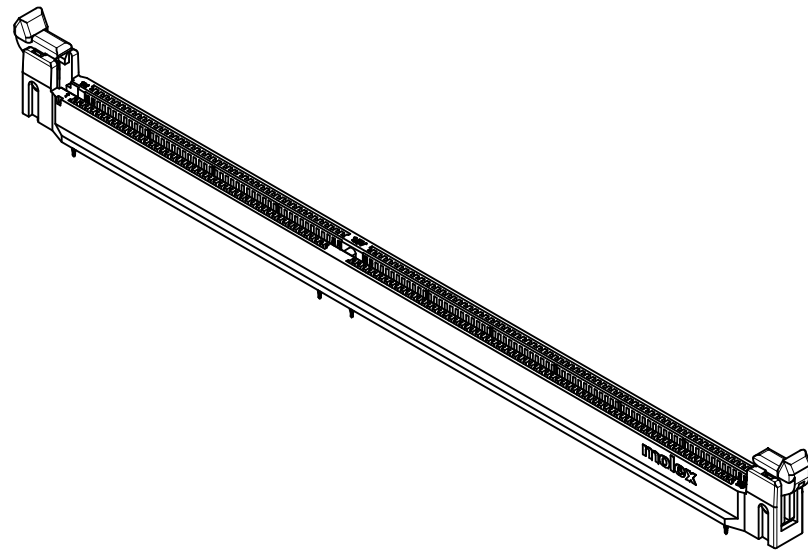
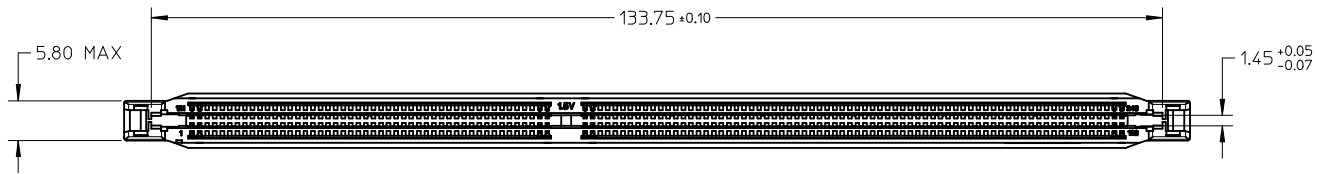


THIS DESIGN IS BASED ON DESIGN OBJECTIVES AND IS STRICTLY TENTATIVE. IT MAY CHANGE BASED ON RESULTS OF ADDITIONAL DESIGN REVIEWS & VERIFICATIONS.

- NOTES:
- MATERIAL:
HOUSING - POLYAMIDE (PA) GLASS FILLED, UL 94V-0, COLOR - BLACK
LATCH - POLYAMIDE (PA) GLASS FILLED, UL 94V-0, COLOR - BLACK
TERMINAL - COPPER ALLOY
 - FINISHES: TERMINAL PLATING SEE TABLE ON SHEET 5
 - PRODUCT SPECIFICATION: PS-78315-001
 - PACKAGING SPECIFICATION: PRODUCT SHALL BE PACKED IN TRAYS
 - CARD SLOT ACCEPTS 1.27 +/- 0.10MM MODULE THICKNESS (MEASURED FROM PC PADS)
6. MOLEX LOGO, DATE & PART NUMBERS INDICATED ON HOUSING
7. MODULE SEATING PLANE FROM TOP OF PCB
8. KEEP OUT ZONE RESERVED FOR LATCH

ADDED OPTION EC NO: S2009-0332 DRW: CCTEH CHKD: CGTAN APPR: SHLENI	2009/05/25 2009/05/25 2009/05/27	DESCRIPTION REV	QUALITY SYMBOLS	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE NTS	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION		
			$\nabla=0$ $\square=0$	mm	INCH	DRAWN BY CMTEO	DATE 2008/07/17	TITLE DDR3 DIMM (LSP, VLP) 1.00MM PITCH, 240 CKTS VERTICAL P/F, LOWLLCR				
				4 PLACES ± --- ± ---	3 PLACES ± --- ± ---	CHECKED BY CCTEH	DATE 2008/07/30	MOLEX INCORPORATED				
				2 PLACES ± 0.20 ± ---	1 PLACE ± --- ± ---	APPROVED BY SHLENI	DATE 2008/08/01	DOCUMENT NO. SD-78315-001				
DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS				ANGULAR ± 1 °		SEE TABLE		SHEET NO. 1 OF 6				
						THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION						

10 9 8 7 6 5 4 3 2 1



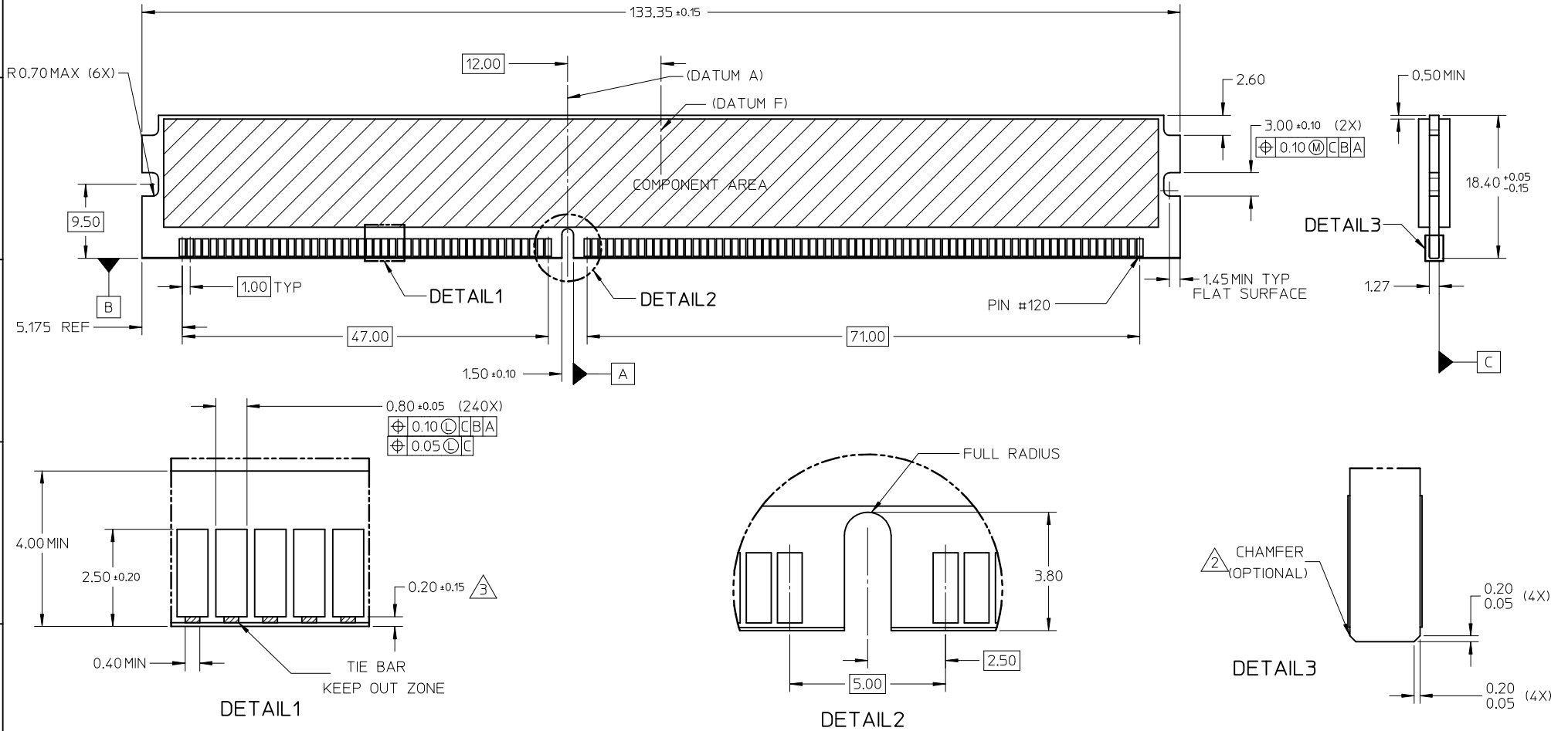
MINIMUM ROW TO ROW SPACING RECOMMENDATION
(USING 4.00MM MODULE CARD)

ADDED OPTION EC NO: S2009-0332 DRWN: CCTEH 2009/05/25 CHKD: CGTAN 2009/05/25 APPR: SHLENI 2009/05/27	QUALITY SYMBOLS ▽=0 ◻=0	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE NTS	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION		
			mm	INCH	DRAWN BY CMTEO	DATE 2008/07/17	TITLE DDR3 DIMM (LSP, VLP) 1.00MM PITCH, 240 CKTS VERTICAL P/F, LOWLLCR			
		4 PLACES	± ---	± ---	CHECKED BY CCTEH	DATE 2008/07/30	MOLEX INCORPORATED			
		3 PLACES	± ---	± ---	APPROVED BY SHLENI	DATE 2008/08/01	MATERIAL NO.	DOCUMENT NO.	SHEET NO.	
	2 PLACES	± 0.20	± ---	DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		SEE TABLE		SD-78315-001		
	1 PLACE	± ---	± ---	ANGULAR ± 1 °		THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION		2 OF 6		

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009MODULE CARD
 DDR3 DUAL INLINE MEMORY MODULE FAMILY 1.00 CONTACT CENTERS
 (JEDEC MO-269, ISSUE A, 12/05)



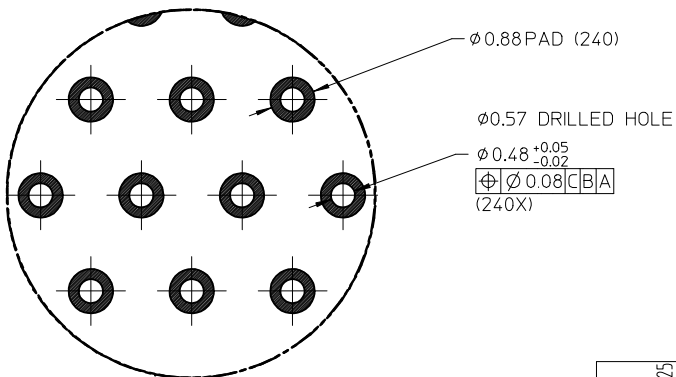
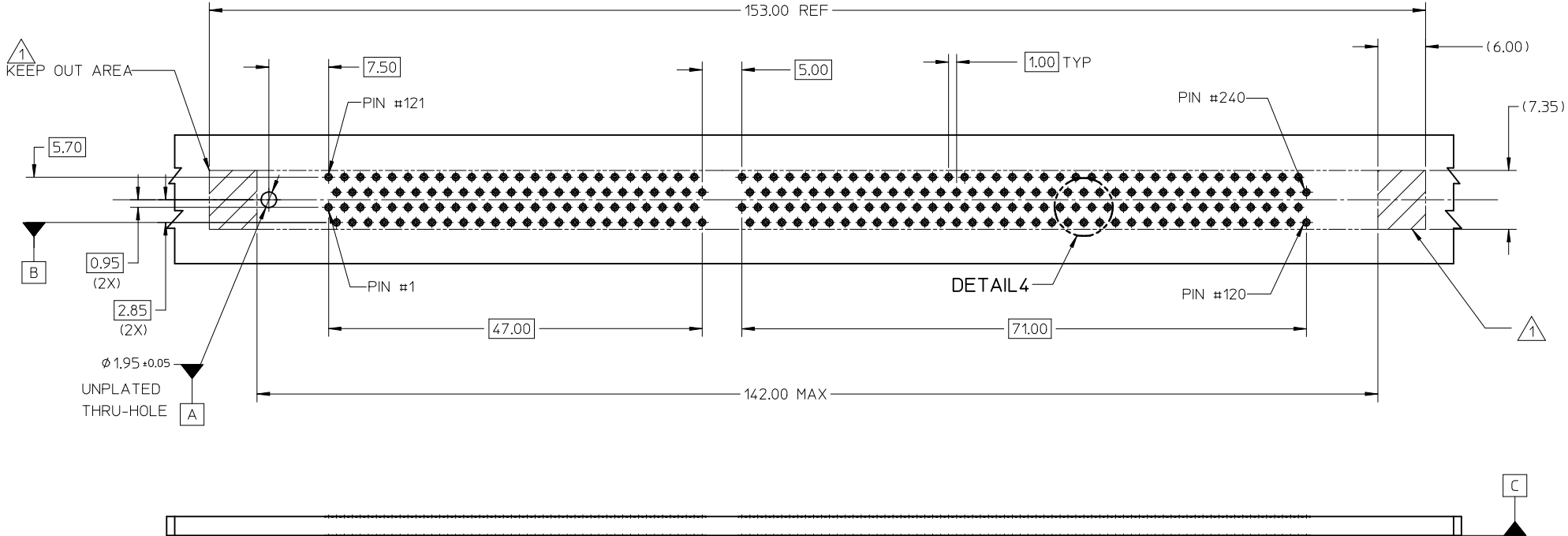
- NOTES:
- RECOMMENDED PLATING FOR CONTACT PADS:
 PREFERRED: 0.76 MICROMETERS GOLD PLATING MIN
 OVER 2.00 MICROMETERS NICKEL
 ALTERNATIVE: 0.05-0.75 MICROMETERS GOLD PLATING
 OVER 2.00 MICROMETERS NICKEL MUST
 USE AN ELECTRONIC CONTACT GRADE
 CORROSIVE BARRIER LUBRICANT
 - CHAMFER IS OPTIONAL AND IS NOT TO HIT THE GOLD PADS
 - LEADING EDGE OF GOLD PADS SPECIFIED BY KEEPOUT ZONE
 SHALL BE FREE OF BURRS AND EXTERNAL TIE BARS

ADDED OPTION EC NO: S2009-0332 DRWN: CCTEH 2009/05/25 CHKD: CGTAN 2009/05/25 APPR: SHLENI 2009/05/27	QUALITY SYMBOLS ▽=0 Ⓢ=0	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE NTS	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION		
		4 PLACES ± --- ± ---	mm INCH	DRAWN BY CMTEO	DATE 2008/07/17	TITLE DDR3 DIMM (LSP, VLP) 1.00MM PITCH, 240 CKTS VERTICAL P/F, LOWLLCR				
		3 PLACES ± --- ± ---		CHECKED BY CCTEH	DATE 2008/07/30	MOLEX INCORPORATED				
		2 PLACES ± 0.20 ± --- 1 PLACE ± --- ± ---		APPROVED BY SHLENI	DATE 2008/08/01	MATERIAL NO. SEE TABLE	DOCUMENT NO. SD-78315-001	SHEET NO. 3 OF 6		
DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		SIZE A3		THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION						

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10 9 8 7 6 5 4 3 2 1

KEEP OUT AREA



DETAIL 4

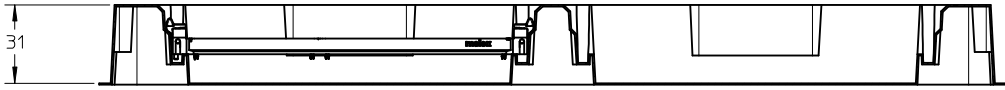
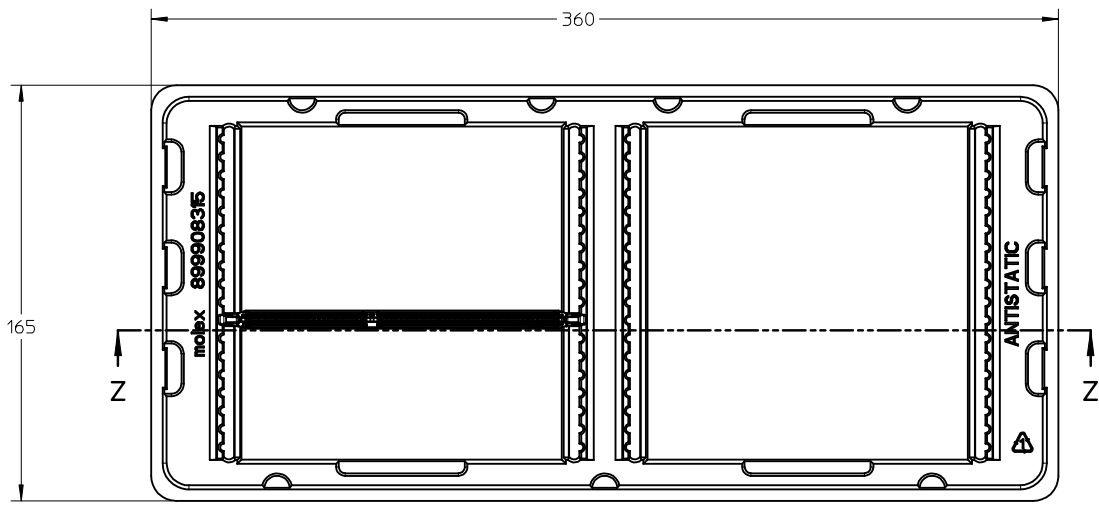
NOTES:
 1. KEEP-OUT AREA IS THE AREA WHERE THE CONNECTOR (INCLUDING LATCH) IS MOUNTED ON THE PCB

ADDED OPTION EC NO: S2009-0332 DRWN: CCTEH 2009/05/25 CHKD: CGTAN 2009/05/25 APPR: SHLENI 2009/05/27	QUALITY SYMBOLS ▽=0 ◻=0	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY	SCALE NTS	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION			
		mm	INCH	DRAWN BY	DATE	TITLE				
		4 PLACES	± ---	± ---	CMTEO	2008/07/17	DDR3 DIMM (LSP, VLP)			
		3 PLACES	± ---	± ---	CCTEH	2008/07/30	1.00MM PITCH, 240 CKTS			
	2 PLACES	± 0.20	± ---	APPROVED BY		MOLEX INCORPORATED				
	1 PLACE	± ---	± ---	SHLENI	2008/08/01	DOCUMENT NO. SD-78315-001				
	ANGULAR ± 1 °			MATERIAL NO.		SHEET NO. 4 OF 6				
DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS				SEE TABLE		THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION				

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VIEW FOR PACKAGING TRAY



SECTION Z-Z




NOTE:

1. NO. OF CAVITY - 18 X 2 =36

ADDED OPTION EC NO: S2009-0332 U DRWN: CCTEH 2009/05/25 CHKD: CGTAN 2009/05/25 APPR: SHLENI 2009/05/27	DESCRIPTION QUALITY SYMBOLS ▽=0 ◻=0	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE	SCALE	DESIGN UNITS	THIRD ANGLE PROJECTION			
				MM ONLY	NTS	METRIC				
				mm	INCH	DRAWN BY	DATE	TITLE		
		4 PLACES	± ---	± ---		CMTEO	2008/07/17	DDR3 DIMM (LSP, VLP)		
3 PLACES	± ---	± ---		CHECKED BY	DATE	1.00MM PITCH, 240 CKTS				
2 PLACES	± 0.20	± ---		CMTEH	2008/07/30	VERTICAL P/F, LOWLLCR				
1 PLACE	± ---	± ---		APPROVED BY	DATE	MOLEX INCORPORATED				
ANGULAR ± 1 °				SHLENI	2008/08/01	MATERIAL NO. DOCUMENT NO.				
DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS				SEE TABLE		SD-78315-001				
				SIZE	THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION					
				A3						
						SHEET NO.		5 OF 6		

9 8 7 6 5 4 3 2 1

PART NO.	KEY POS.	DIM 'P'	RECOMMENDED PCB THICKNESS	PLATING OPTION	
				CONTACT AREA	TAIL AREA
78315-0001	CENTER (1.5V)	1.85	2.40	0.76 MICROMETER/ 30 MICROINCH MIN. GOLD OVER 1.27 MICROMETER/ 50 MICROINCH MIN. NICKEL UNDERPLATE	0.38 TO 1.52 MICROMETER/15 TO 60 MICROINCH MIN TIN (MATT) OVER 1.27 MICROMETER/ 50 MICROINCH MIN. NICKEL UNDERPLATE
78315-0201				0.76 MICROMETER/ 30 MICROINCH MIN. GOLD OVER 1.27 MICROMETER/ 50 MICROINCH MIN. NICKEL UNDERPLATE	0.38 TO 1.52 MICROMETER/15 TO 60 MICROINCH MIN TIN/LEAD (BRIGHT) OVER 1.27 MICROMETER/ 50 MICROINCH MIN. NICKEL UNDERPLATE
78315-0011		2.85	2.60	0.76 MICROMETER/ 30 MICROINCH MIN. GOLD OVER 1.27 MICROMETER/ 50 MICROINCH MIN. NICKEL UNDERPLATE	0.38 TO 1.52 MICROMETER/15 TO 60 MICROINCH MIN TIN (MATT) OVER 1.27 MICROMETER/ 50 MICROINCH MIN. NICKEL UNDERPLATE

ADDED OPTION EC NO: S2009-0332 DRWN: CCTEH 2009/05/25 CHKD: CGTAN 2009/05/25 APPR: SHLENI 2009/05/27	QUALITY SYMBOLS  = 0  = 0.20	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE NTS	DESIGN UNITS METRIC	 THIRD ANGLE PROJECTION	
		4 PLACES ± --- ± ---	DRAWN BY CMTEO	DATE 2008/07/17	TITLE DDR3 DIMM (LSP, VLP) 1.00MM PITCH, 240 CKTS VERTICAL P/F, LOWLLCR				
		3 PLACES ± --- ± ---	CHECKED BY CCTEH	DATE 2008/07/30	MOLEX INCORPORATED				
		2 PLACES ± 0.20 ± --- 1 PLACE ± --- ± --- ANGULAR ± 1 °	APPROVED BY SHLENI	DATE 2008/08/01	MATERIAL NO. SEE TABLE	DOCUMENT NO. SD-78315-001	SHEET NO. 6 OF 6		

DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS

SIZE A3 THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION